

**AMENDMENTS TO THE CLAIMS:**

*This listing of claims will replace all prior versions, and listings, of claims in the application:*

1-2. (Canceled)

3. (Original) A flexible substrate to be connected to a semiconductor chip, comprising:  
an insulting film;

a plurality of internal connecting electrodes, provided on a surface of the insulating film,  
to be connected to the semiconductor chip;

a plurality of wires, provided on the surface of the insulating film, for connecting the  
internal connecting electrodes and a plurality of external connecting electrodes to be connected  
to external devices; and

a protective film for coating the internal connecting electrodes, the wires and the surface  
of the insulating film.

4. (Original) A semiconductor device comprising:

a semiconductor chip; and

a flexible substrate connected to the semiconductor chip,

the flexible substrate including:

an insulating film;

a plurality of internal connecting electrodes, provided on a surface of the  
insulating film, to be connected to the semiconductor chip;

a plurality of wires, provided on the surface of the insulating film, for connecting the internal connecting electrodes and a plurality of external connecting electrodes to be connected to external devices; and

a protective film for coating the internal connecting electrodes, the wires and the surface of the insulating film,

wherein the semiconductor chip is mounted by positioning an element surface so as to face a surface of the flexible substrate and connecting the element surface to the internal connecting electrodes of the flexible substrate.

5. (Original) The semiconductor device according to claim 4, wherein a periphery of the semiconductor chip is sealed with synthetic resin.

6. (New) The semiconductor device of claim 4, wherein the protective film comprises a solder resist and directly contacts respective upper surfaces of each of: the internal connecting electrodes, the wires, and the insulating film.

7. (New) The semiconductor device of claim 4, wherein the chip is an LCD driver chip.

8. (New) A semiconductor device comprising:

a semiconductor chip; and

a flexible substrate supporting the semiconductor chip,

the flexible substrate including:

an insulating film;

a plurality of internal connecting electrodes, provided on a surface of the insulating film and at least partially under the chip, to be electrically connected to the semiconductor chip;

a plurality of wires, provided on the surface of the insulating film, for connecting the internal connecting electrodes and a plurality of external connecting electrodes to be connected to external devices; and

a protective film comprising a solder resist for at least partially coating each of: the internal connecting electrodes, the wires and the surface of the insulating film,

wherein the semiconductor chip is mounted by positioning an element surface so as to face a surface of the flexible substrate and connecting the element surface to the internal connecting electrodes of the flexible substrate.

9. (New) The semiconductor device according to claim 8, wherein a periphery of the semiconductor chip is sealed with synthetic resin.

10. (New) The semiconductor device of claim 8, wherein the protective film comprising the solder resist directly contacts respective upper surfaces of each of: the internal connecting electrodes, the wires, and the insulating film.

11. (New) The semiconductor device of claim 8, wherein the chip is an LCD driver chip.